



US00D388066S

United States Patent [19]
Ishihara

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[54] **IC MODULE**
[75] **Inventor: Tomiaki Ishihara, Yokohama, Japan**
[73] **Assignee: Kabushiki Kaisha Toshiba, Kawasaki, Japan**
[**] **Term: 14 Years**

D. 368,903 4/1996 Ohmori et al. D14/117
D. 369,156 4/1996 Ohmori et al. D14/117
D. 369,157 4/1996 Ohmori et al. D14/117

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[21] **Appl. No.: 62,837**
[22] **Filed: Nov. 27, 1996**

[57] **CLAIM**
The ornamental design for an IC module, as shown and described.

[30] **Foreign Application Priority Data**
May 29, 1996 [JP] Japan 8-15401
[51] **LOC (6) Cl. 14-02**
[52] **U.S. Cl. D14/114; D14/117**
[58] **Field of Search D14/114, 117, D14/107; 235/378-380, 492, 487; 257/731, 669**

DESCRIPTION

FIG. 1 is a front, bottom and right side perspective view of an IC module showing my new design;
FIG. 2 is a front elevational view thereof;
FIG. 3 is a right side elevational view thereof, the opposite side being a mirror image;
FIG. 4 is a top plan view thereof;
FIG. 5 is a bottom plan view thereof; and,
FIG. 6 is a rear elevational view thereof.

[56] **References Cited**
U.S. PATENT DOCUMENTS
D. 357,909 5/1995 Gloton D14/114

1 Claim, 1 Drawing Sheet

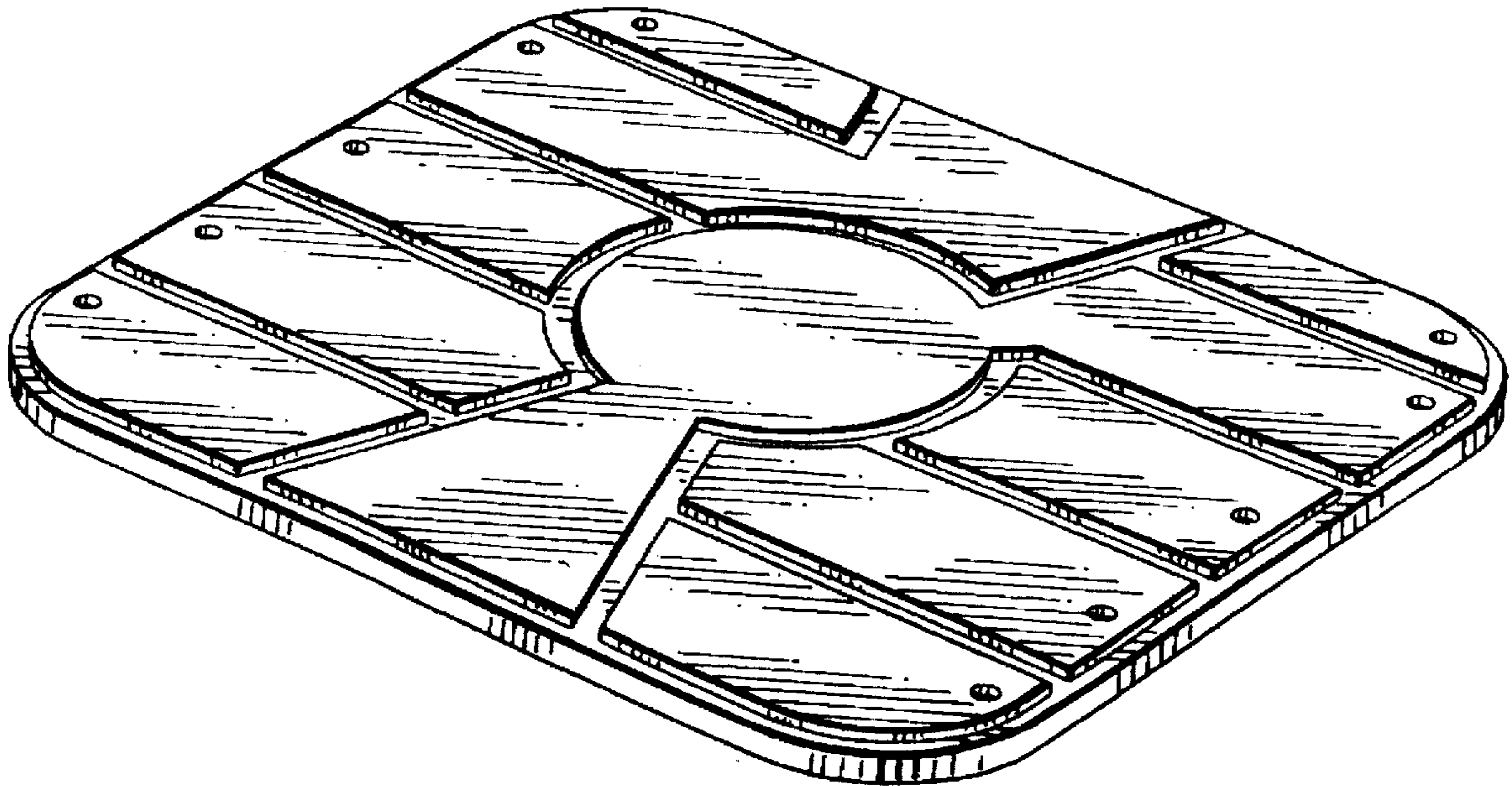


FIG. 1

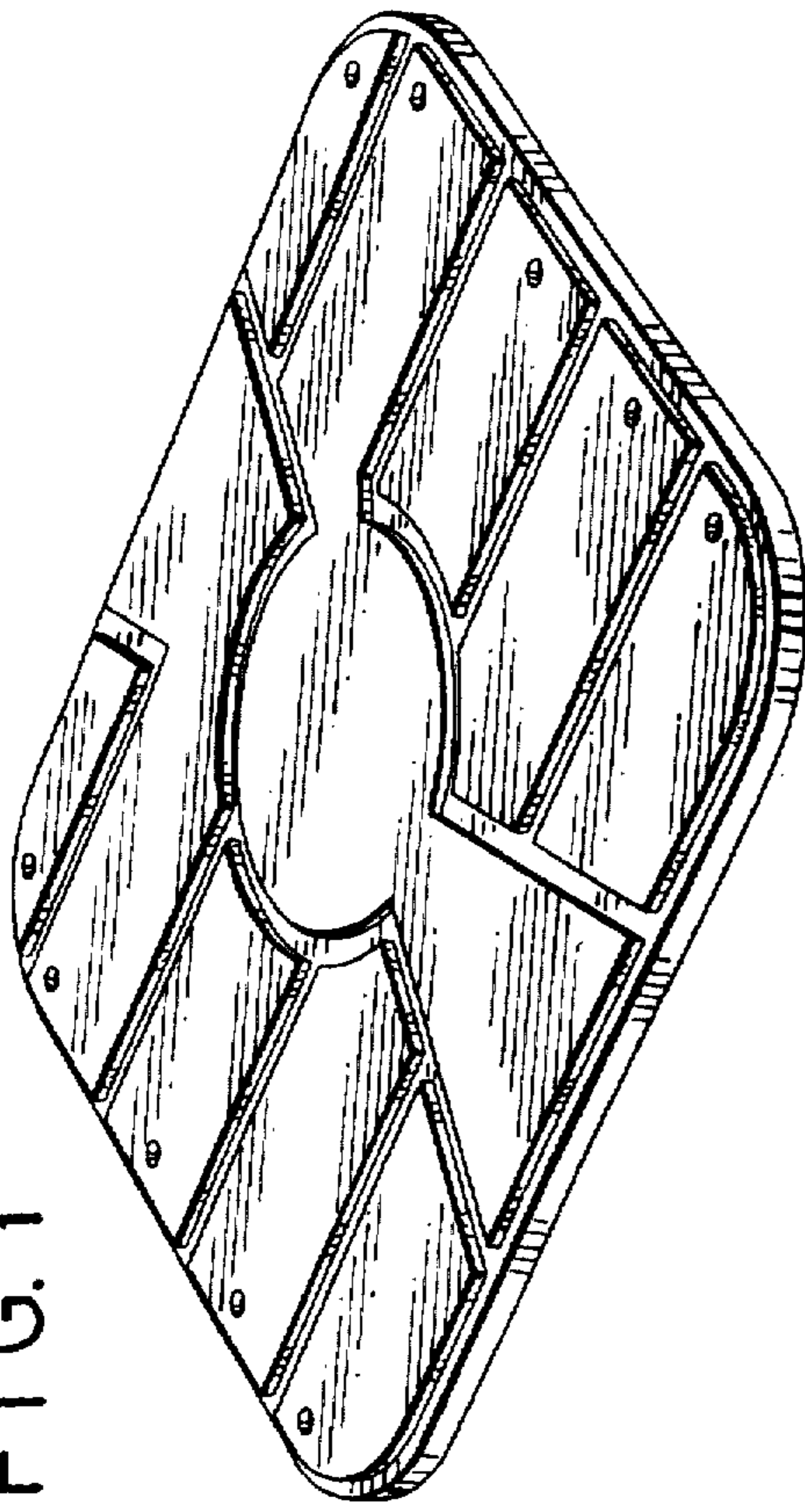


FIG. 2

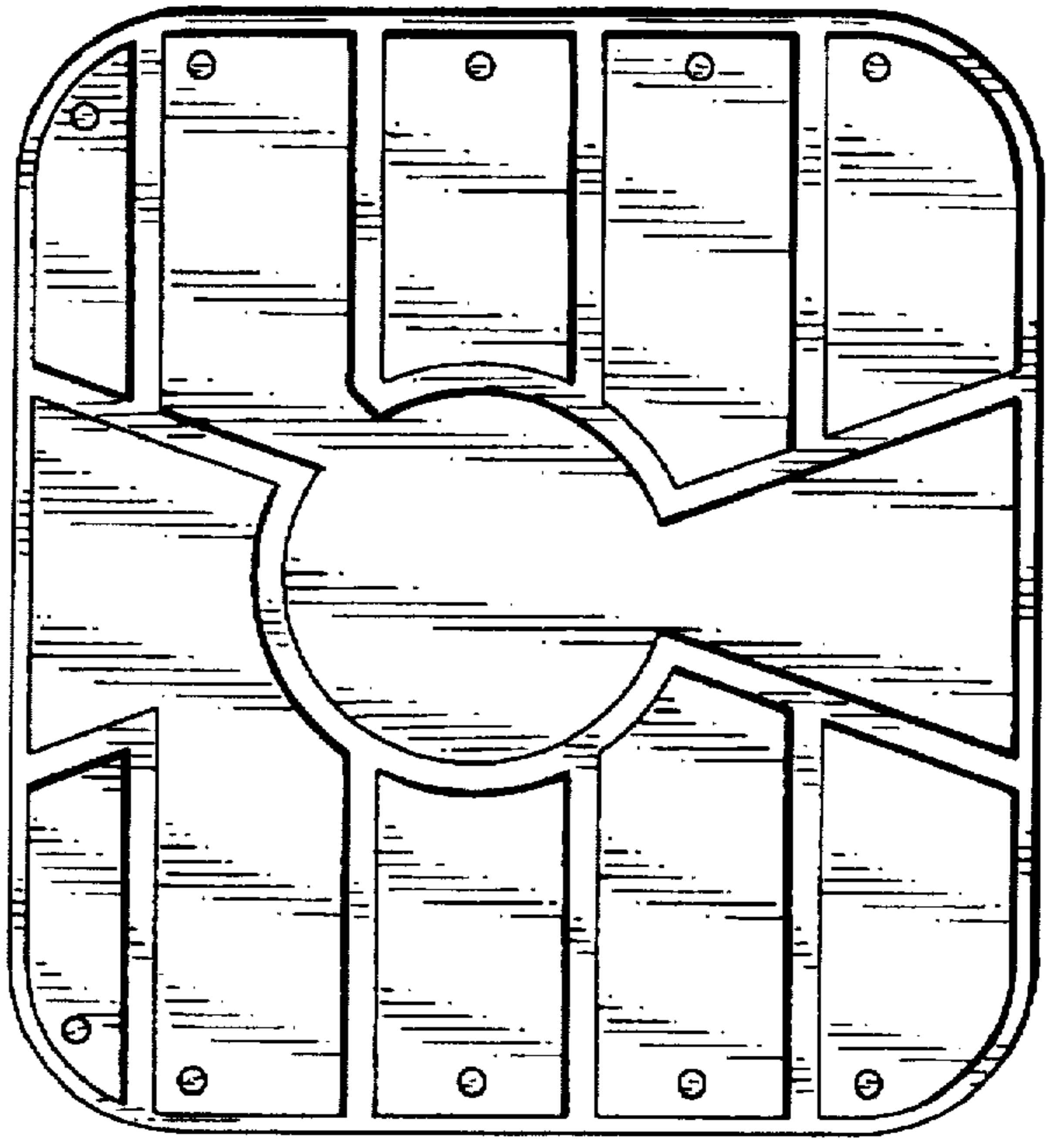


FIG. 3

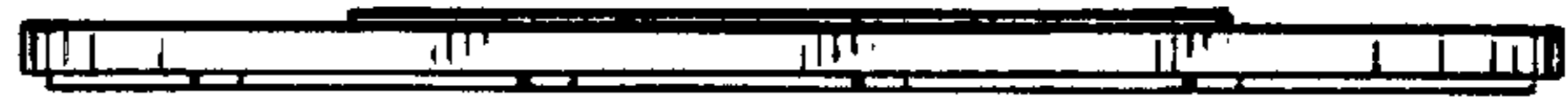


FIG. 4

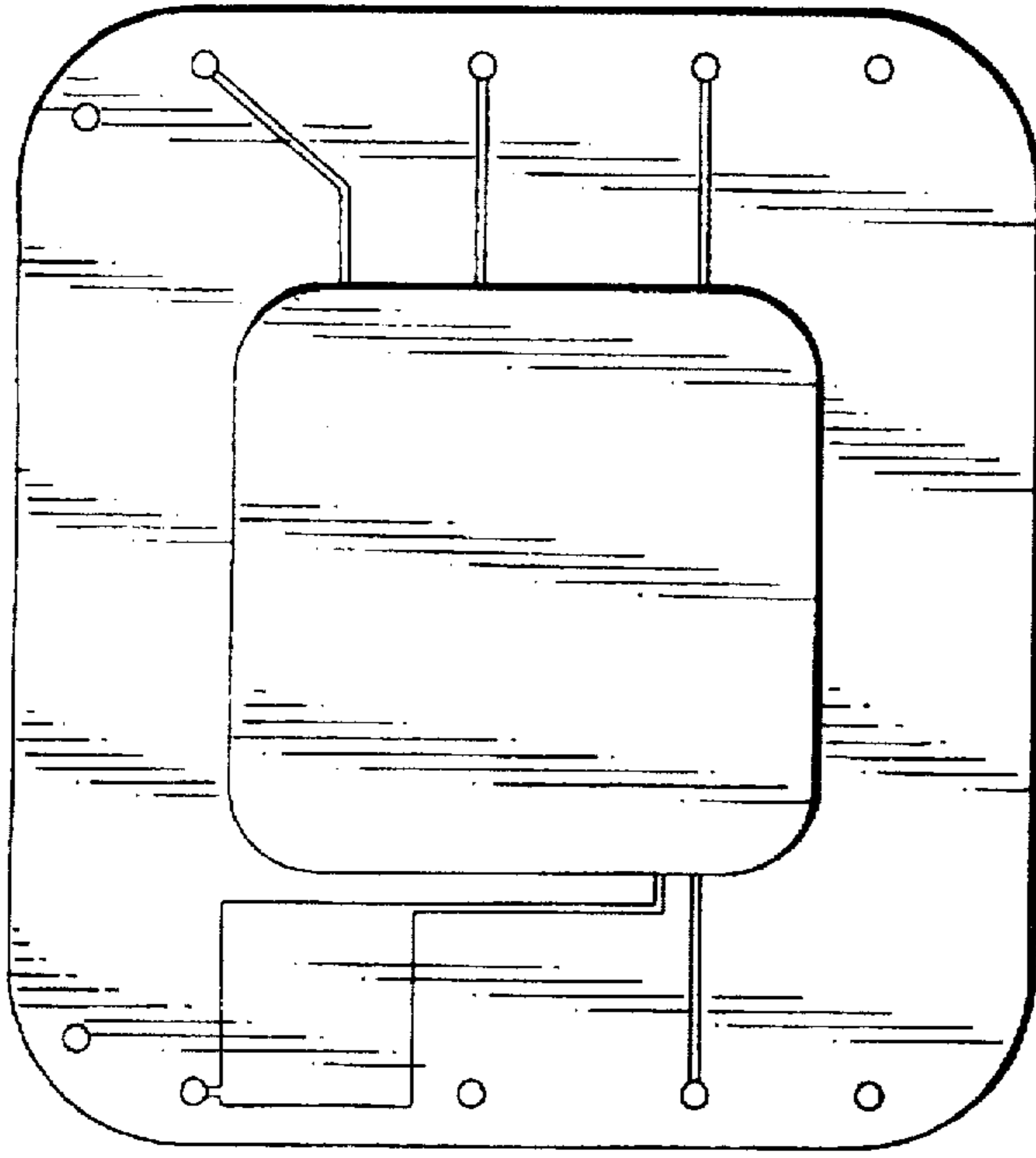


FIG. 5



FIG. 6

